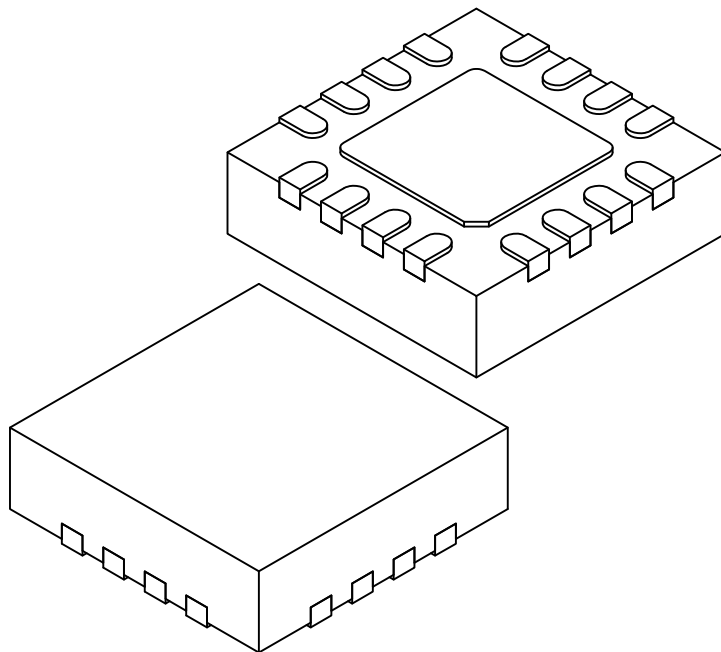


16-Lead Very Thin Plastic Quad Flat, No Lead Package (RDB) - 3x3x0.9 mm Body [VQFN] With 1.7 mm Exposed Pad; Atmel Legacy Package ZPX

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	16		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.035	0.05
Terminal Thickness	A3	0.21 REF		
Overall Length	D	3.00 BSC		
Exposed Pad Length	D2	1.60	1.70	1.80
Overall Width	E	3.00 BSC		
Exposed Pad Width	E2	1.60	1.70	1.80
Terminal Width	b	0.20	0.25	0.30
Terminal Length	L	0.35	0.40	0.45
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.